

ABSTRACT OF THE DISCLOSURE

A first semiconductor chip is attached to a first side of a printed circuit board, and a second semiconductor chip is attached to a second side of the printed circuit board opposite the first side of the printed circuit board. A mold is then used to form a first mold cavity which contains the first semiconductor chip over the first side of the printed circuit board, and to form a second mold cavity which contains the second semiconductor chip over the second side of the printed circuit board. The first and second mold cavities are simultaneously filled with a fill material via a mold inlet, where the mold inlet is at least partially defined through an aperture in the printed circuit board from the first side to the second side.